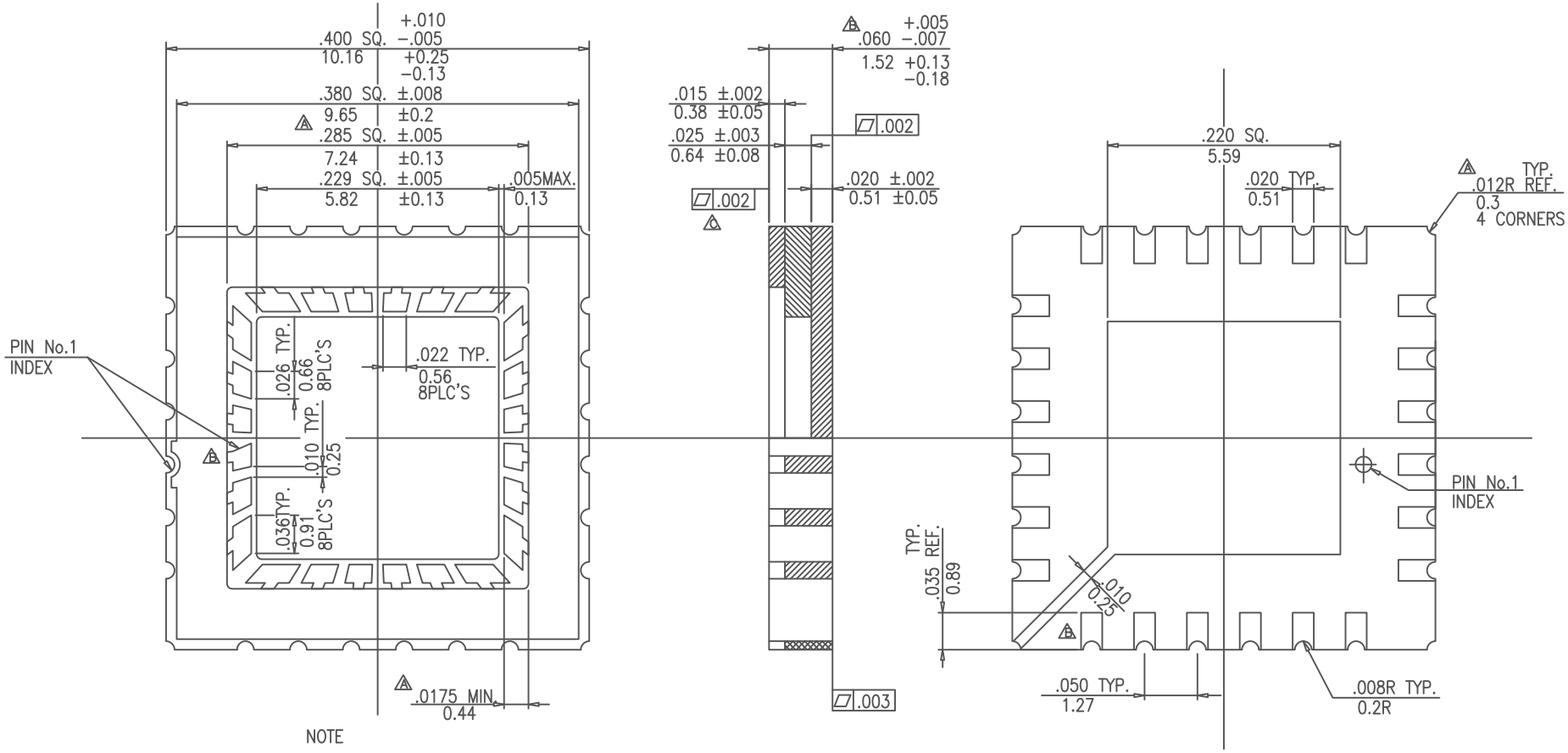
SSM P/N LCC02411



NOTE

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH (1.5MICRON)MIN. THK. OVER 100 MICRO INCH (2.54 MICRON)NOM. THICKNESS OF NICKEL UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER.
2. FLATNESS PERTAINS METALLIZED PAD ONLY.
3. LEAD TO LEAD LEAKAGE MUST NOT EXCEED 5 NANO AMPS AT 100 VDC.
4. NO PIN CONNECTED TO SEAL AREA AND DIE ATTACH PAD. (ZERO GROUND)
5. PART NO

PART NO.	HEAT SINK METALLIZATION		
01	WITHOUT	FC−24CNB	S=0
02	WITH	FC−24CA	D=0

MODIFICATIONS					
	ADD:TABLE,CHANGE: .003 → .002	83.5.23	T.I	O.M	Y.S
	CHANGED : NOTE:1 BONDING PAD SOLDER PAD .060±.006 → .060 +.005 −.007	79.8.25	N.U	O.M	
	CHANGED : .020R REF. TYP. → .012R REF. TYP. MATERIAL				
	CHANGED : .294±.006 → .285±.005 .022MIN → .0175MIN	79.7.26	N.U	O.M	
	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME: 24 LEAD CHIP CARRIER

SCALE: 10/1

MATERIAL: KYOCERA A−440

TOLERANCES: UNLESS OTHERWISE SPECIFIED ±1% N.L.T ±.005(0.13) THIRD ANGLE PROJECTION

KYOCERA

KYOCERA CORPORATION KYOTO JAPAN

FCS−90387−C

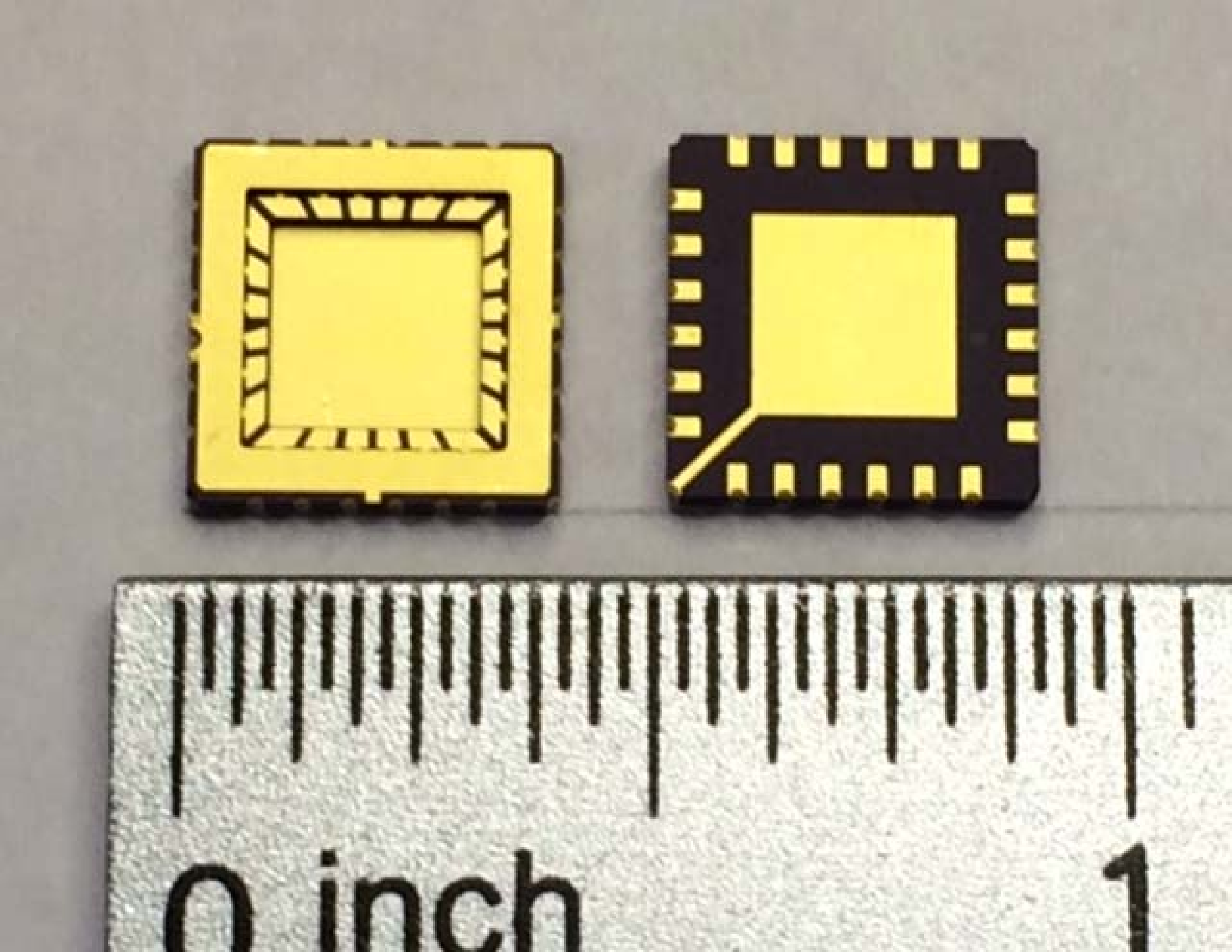
DRAWN	CHECKED	APPROVED	DATE
S.M	UE / K.H	M.S	MAR.04.'99

DRAWING NO. PB−92234−C

SHEET 1/1

SPECTRUM SEMICONDUCTOR MATERIALS, INC.

www.spectrum-semi.com Phone: 408-435-5555 Fax: 408-435-8226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